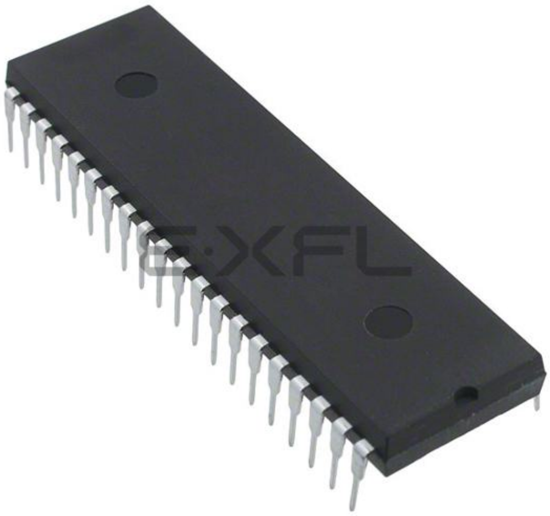

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

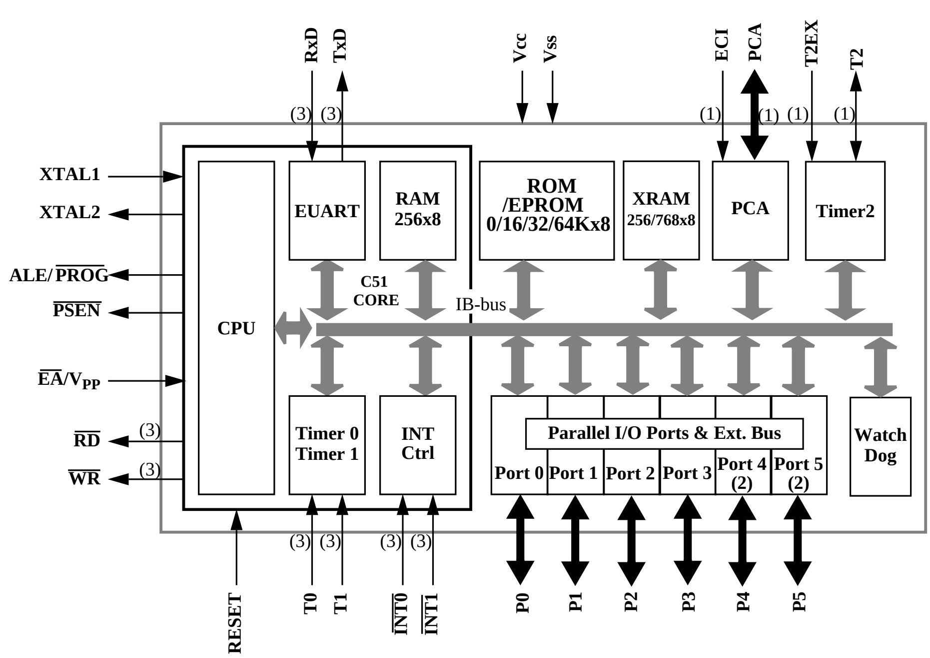
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c51rd2-lca

PDIL40 PLCC44 VQFP44 1.4	ROM (bytes)	EPROM (bytes)	XRAM (bytes)	TOTAL RAM (bytes)	I/O
TS80C51RA2 **TS80C51RD2**	0 0	0 0	256 768	512 1024	32 32
TS83C51RB2 **TS83C51RC2** **TS83C51RD2**	16k 32k 64k	0 0 0	256 256 768	512 512 1024	32 32 32
TS87C51RB2 **TS87C51RC2** **TS87C51RD2**	0 0 0	16k 32k 64k	256 256 768	512 512 1024	32 32 32

PLCC68 VQFP64 1.4	ROM (bytes)	EPROM (bytes)	XRAM (bytes)	TOTAL RAM (bytes)	I/O
TS80C51RD2	0	0	768	1024	48
TS83C51RD2	64k	0	768	1024	48
TS87C51RD2	0	64k	768	1024	48

3. Block Diagram

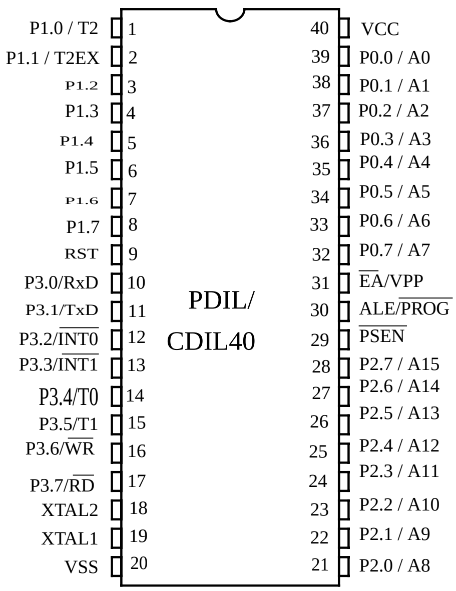


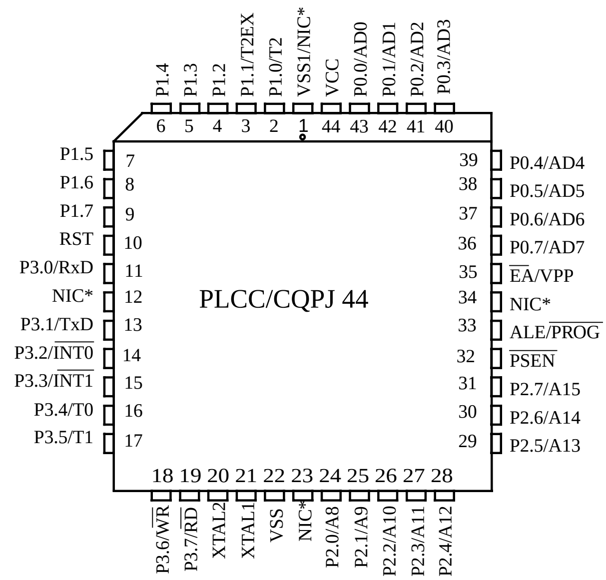
(1): Alternate function of Port 1

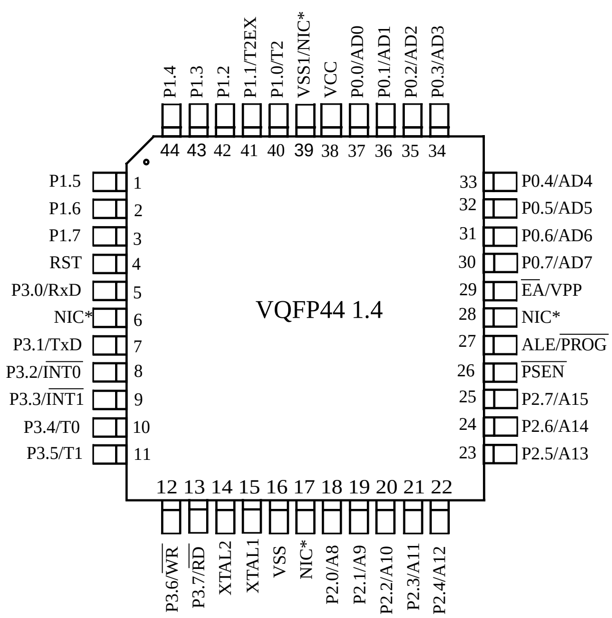
(2): Only available on high pin count packages

(3): Alternate function of Port 3

5. Pin Configuration







*NIC: No Internal Connection

	PLCC68	SQUARE VQFP64 1.4
P3.2	40	29
P3.3	41	30
P3.4	42	31
P3.5	43	32
P3.6	45	34
P3.7	47	36
RESET	30	21
ALE/PROG	68	56
PSEN	67	55
EA/VPP	2	58
XTAL1	49	38
XTAL2	48	37
P4.0	20	11
P4.1	24	15
P4.2	26	17
P4.3	44	33
P4.4	46	35
P4.5	50	39
P4.6	53	42
P4.7	57	46
P5.0	60	49
P5.1	62	51
P5.2	63	52
P5.3	7	62
P5.4	8	63
P5.5	10	1
P5.6	13	4
P5.7	16	7

6.2. Dual Data Pointer Register Ddptr

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 4.) that allows the program code to switch between them (Refer to Figure 3).

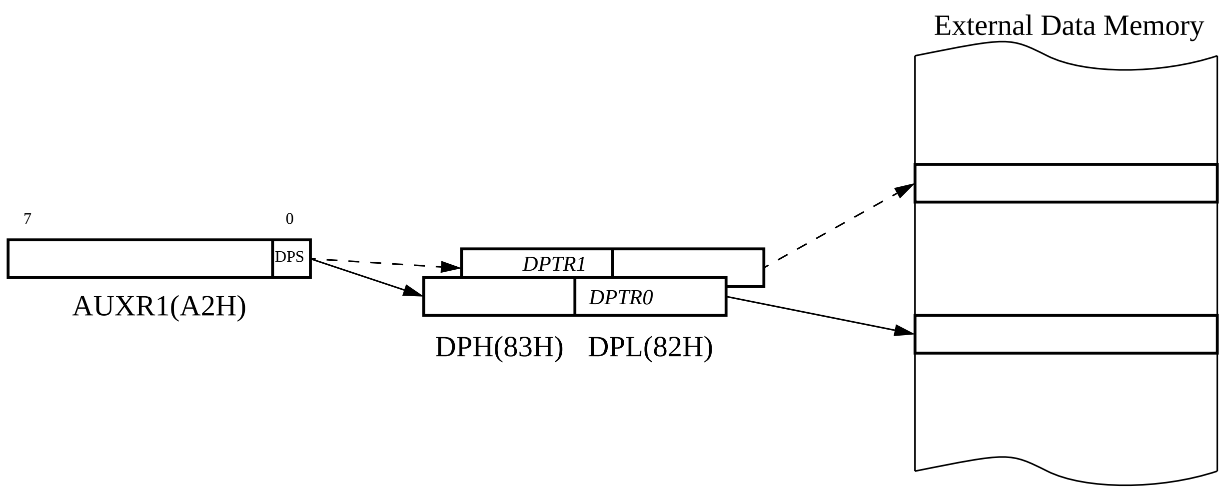


Figure 3. Use of Dual Pointer

Table 4. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	-	-	DPS
	Reset value	X	X	X	X	0	X	X	0

Symbol	Function	
-	Not implemented, reserved for future use.[a]	
DPS	Data Pointer Selection.	
	DPS	**Operating Mode**
	0	DPTR0 Selected
	1	DPTR1 Selected
GF3	This bit is a general purpose user flag[b].	

a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.
b. GF3 will not be available on first version of the RC devices.

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a ’source’ pointer and the other one as a "destination" pointer.

6.3. Expanded RAM (XRAM)

The TS80C51Rx2 provide additional Bytes of ramdom access memory (RAM) space for increased data parameter handling and high level language usage.

RA2, RB2 and RC2 devices have 256 bytes of expanded RAM, from 00H to FFH in external data space; RD2 devices have 768 bytes of expanded RAM, from 00H to 2FFH in external data space.

The TS80C51Rx2 has internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared in the AUXR register. (See Table 5.)

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. **For example: MOV 0A0H, # data** ,accesses the SFR at location 0A0H (which is P2).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM. **For example: MOV @R0, # data** where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).
- The 256 or 768 XRAM bytes can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 or 768 bytes of external data memory.
- With EXTRAM = 0, the XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. **An access to XRAM will not affect ports P0, P2, P3.6 ($\overline{\text{WR}}$) and P3.7 ($\overline{\text{RD}}$)**. **For example, with EXTRAM = 0, MOVX @R0, # data** where R0 contains 0A0H, accesses the XRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) (higher than 2FFH (i.e. 0300H to FFFFH for RD devices) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address busses, and P3.6 and P3.7 as write and read timing signals. Refer to Figure . For RD devices, accesses to expanded RAM from 100H to 2FFH can only be done thanks to the use of DPTR.
- With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an eight-bit address multiplexed with data on Port0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a sixteen-bit address. Port2 outputs the high-order eight address bits (the contents of DPH) while Port0 multiplexes the low-order eight address bits (DPL) with data. MOVX @ Ri and MOVX @DPTR will generate either read or write signals on P3.6 ($\overline{\text{WR}}$) and P3.7 ($\overline{\text{RD}}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.

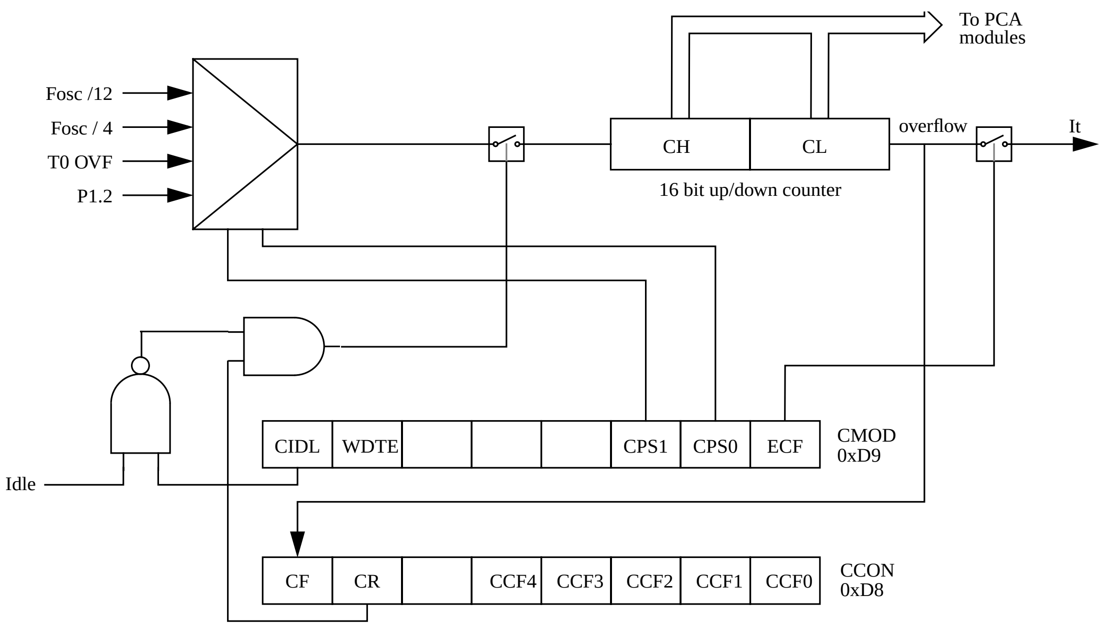


Figure 7. PCA Timer/Counter

Table 8. CMOD: PCA Counter Mode Register

CMOD Address 0D9H	CIDL	WDTE	-	-	-	CPS1	CPS0	ECF
Reset value	0	0	X	X	X	0	0	0

Symbol	Function		
CIDL	Counter Idle control: CIDL = 0 programs the PCA Counter to continue functioning during idle Mode. CIDL = 1 programs it to be gated off during idle.		
WDTE	Watchdog Timer Enable: WDTE = 0 disables Watchdog Timer function on PCA Module 4. WDTE = 1 enables it.		
-	Not implemented, reserved for future use.[a]		
CPS1	PCA Count Pulse Select bit 1.		
CPS0	PCA Count Pulse Select bit 0.		
	CPS1	**CPS0**	**Selected PCA input.**[b]
	0	0	Internal clock $f_{osc}/12$ (Or $f_{osc}/6$ in X2 Mode).
	0	1	Internal clock $f_{osc}/4$ (Or $f_{osc}/2$ in X2 Mode).
	1	0	Timer 0 Overflow
	1	1	External clock at ECI/P1.2 pin (max rate = $f_{osc}/ 8$)
ECF	PCA Enable Counter Overflow interrupt: ECF = 1 enables CF bit in CCON to generate an interrupt. ECF = 0 disables that function of CF.		

a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.
b. f_{osc} = oscillator frequency

The CMOD SFR includes three additional bits associated with the PCA (See Figure 7 and Table 8).

- The CIDL bit which allows the PCA to stop during idle mode.
- The WDTE bit which enables or disables the watchdog function on module 4.

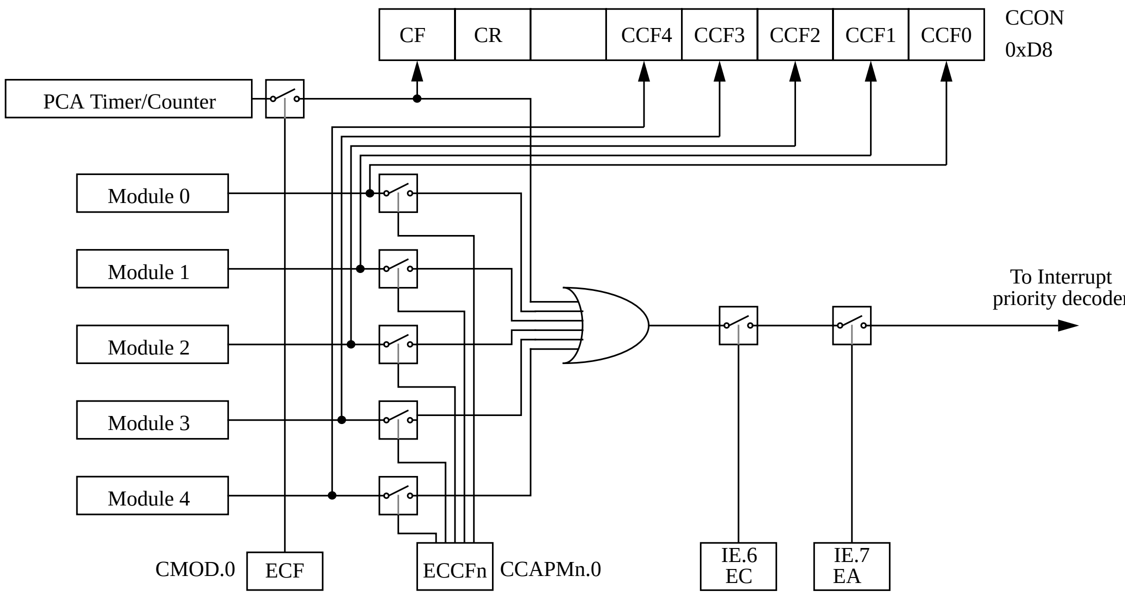


Figure 8. PCA Interrupt System

PCA Modules: each one of the five compare/capture modules has six possible functions. It can perform:

- 16-bit Capture, positive-edge triggered,
- 16-bit Capture, negative-edge triggered,
- 16-bit Capture, both positive and negative-edge triggered,
- 16-bit Software Timer,
- 16-bit High Speed Output,
- 8-bit Pulse Width Modulator.

In addition, module 4 can be used as a Watchdog Timer.

Each module in the PCA has a special function register associated with it. These registers are: CCAPM0 for module 0, CCAPM1 for module 1, etc. (See Table 10). The registers contain the bits that control the mode that each module will operate in.

- The ECCF bit (CCAPMn.0 where n=0, 1, 2, 3, or 4 depending on the module) enables the CCF flag in the CCON SFR to generate an interrupt when a match or compare occurs in the associated module.
- PWM (CCAPMn.1) enables the pulse width modulation mode.
- The TOG bit (CCAPMn.2) when set causes the CEX output associated with the module to toggle when there is a match between the PCA counter and the module's capture/compare register.
- The match bit MAT (CCAPMn.3) when set will cause the CCFn bit in the CCON register to be set when there is a match between the PCA counter and the module's capture/compare register.
- The next two bits CAPN (CCAPMn.4) and CAPP (CCAPMn.5) determine the edge that a capture input will be active on. The CAPN bit enables the negative edge, and the CAPP bit enables the positive edge. If both bits are set both edges will be enabled and a capture will occur for either transition.
- The last bit in the register ECOM (CCAPMn.6) when set enables the comparator function.

Table 11 shows the CCAPMn settings for the various PCA functions.

.

6.5.1. PCA Capture Mode

To use one of the PCA modules in the capture mode either one or both of the CCAPM bits CAPN and CAPP for that module must be set. The external CEX input for the module (on port 1) is sampled for a transition. When a valid transition occurs the PCA hardware loads the value of the PCA counter registers (CH and CL) into the module's capture registers (CCAPnL and CCAPnH). If the CCFn bit for the module in the CCON SFR and the ECCFn bit in the CCAPMn SFR are set then an interrupt will be generated (Refer to Figure 9).

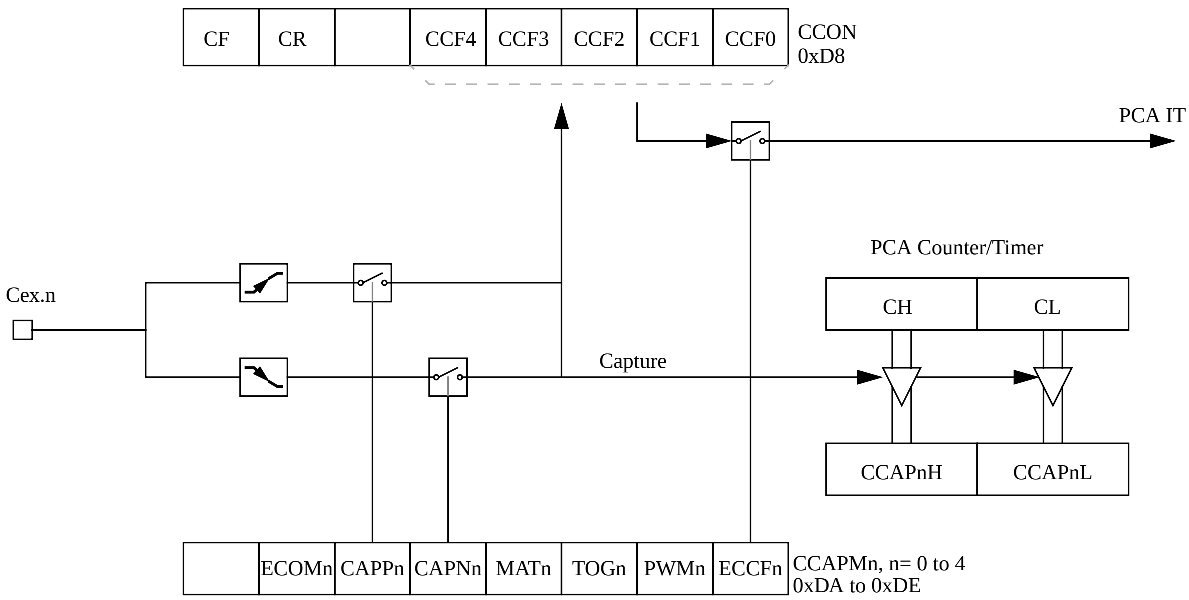


Figure 9. PCA Capture Mode

6.6.5. Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b
Not bit addressable

SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b
Not bit addressable

Table 22. The state of ports during idle and power-down mode

Mode	Program Memory	ALE	$\overline{PSEN}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data*	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	Internal	0	0	Port Data*	Port Data	Port Data	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data

* Port 0 can force a "zero" level. A "one" will leave port floating.

Table 24. WDTPRG Register

WDTPRG Address (0A7h)

7	6	5	4	3	2	1	0
T4	T3	T2	T1	T0	S2	S1	S0

Bit Number	Bit Mnemonic	Description
7	T4	**Reserved** Do not try to set or clear this bit.
6	T3	
5	T2	
4	T1	
3	T0	
2	S2	**WDT Time-out select bit 2**
1	S1	**WDT Time-out select bit 1**
0	S0	**WDT Time-out select bit 0**

S2	S1	S0	Selected Time-out
0	0	0	(2^{14} - 1) machine cycles, 16.3 ms @ 12 MHz
0	0	1	(2^{15} - 1) machine cycles, 32.7 ms @ 12 MHz
0	1	0	(2^{16} - 1) machine cycles, 65.5 ms @ 12 MHz
0	1	1	(2^{17} - 1) machine cycles, 131 ms @ 12 MHz
1	0	0	(2^{18} - 1) machine cycles, 262 ms @ 12 MHz
1	0	1	(2^{19} - 1) machine cycles, 542 ms @ 12 MHz
1	1	0	(2^{20} - 1) machine cycles, 1.05 s @ 12 MHz
1	1	1	(2^{21} - 1) machine cycles, 2.09 s @ 12 MHz

Reset value XXXX X000

6.10.2. WDT during Power Down and Idle

In Power Down mode the oscillator stops, which means the WDT also stops. While in Power Down mode the user does not need to service the WDT. There are 2 methods of exiting Power Down mode: by a hardware reset or via a level activated external interrupt which is enabled prior to entering Power Down mode. When Power Down is exited with hardware reset, servicing the WDT should occur as it normally should whenever the TS80C51Rx2 is reset. Exiting Power Down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service routine.

To ensure that the WDT does not overflow within a few states of exiting of powerdown, it is best to reset the WDT just before entering powerdown.

In the Idle mode, the oscillator continues to run. To prevent the WDT from resetting the TS80C51Rx2 while in Idle mode, the user should always set up a timer that will periodically exit Idle, service the WDT, and re-enter Idle mode.

8. TS87C51RB2/RC2/RD2 EPROM

8.1. EPROM Structure

The TS87C51RB2/RC2/RD2 EPROM is divided in two different arrays:

- the code array: . . . . 16/32/64 Kbytes.
- the encryption array: . . . . 64 bytes.

In addition a third non programmable array is implemented:

- the signature array: . . . . 4 bytes.

8.2. EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

8.2.1. Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

8.2.2. Program Lock Bits

The three lock bits, when programmed according to Table 29.8.2.3. , will provide different level of protection for the on-chip code and data.

Table 29. Program Lock bits

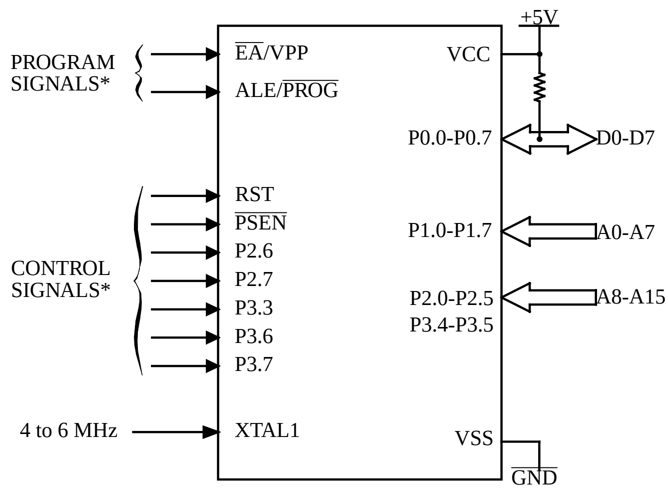
Program Lock Bits				Protection description
Security level	LB1	LB2	LB3	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed,
P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

8.2.3. Signature bytes

The TS87C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.



* See Table 31. for proper value on these inputs

Figure 18. Set-Up Modes Configuration

8.3.3. Programming Algorithm

The Improved Quick Pulse algorithm is based on the Quick Pulse algorithm and decreases the number of pulses applied during byte programming from 25 to 1.

To program the TS87C51RB2/RC2/RD2 the following sequence must be exercised:

- Step 1: Activate the combination of control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Input the appropriate data on the data lines.
- Step 4: Raise $\overline{EA}$/VPP from VCC to VPP (typical 12.75V).
- Step 5: Pulse ALE/$\overline{PROG}$ once.
- Step 6: Lower $\overline{EA}$/VPP from VPP to VCC

Repeat step 2 through 6 changing the address and data for the entire array or until the end of the object file is reached (See Figure 19.).

8.3.4. Verify algorithm

Code array verify must be done after each byte or block of bytes is programmed. In either case, a complete verify of the programmed array will ensure reliable programming of the TS87C51RB2/RC2/RD2.

P 2.7 is used to enable data output.

To verify the TS87C51RB2/RC2/RD2 code the following sequence must be exercised:

- Step 1: Activate the combination of program and control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Read data on the data lines.

Repeat step 2 through 3 changing the address for the entire array verification (See Figure 19.)

The encryption array cannot be directly verified. Verification of the encryption array is done by observing that the code array is well encrypted.

10. Electrical Characteristics

10.1. Absolute Maximum Ratings (1)

Ambiant Temperature Under Bias:	
C = commercial	0°C to 70°C
I = industrial	-40°C to 85°C
Storage Temperature	-65°C to + 150°C
Voltage on V_{CC} to V_{SS}	-0.5 V to + 7 V
Voltage on V_{PP} to V_{SS}	-0.5 V to + 13 V
Voltage on Any Pin to V_{SS}	-0.5 V to V_{CC} + 0.5 V
Power Dissipation	1 W(2)

NOTES

1. *Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.*
2. *This value is based on the maximum allowable die temperature and the thermal resistance of the package.*

10.2. Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel Wireless & Microcontrollers new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel Wireless & Microcontrollers presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

```
Label:    SJMP Label (80 FE)
```

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

10.3. DC Parameters for Standard Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.
TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5 V ± 10%; F = 0 to 40 MHz.

Table 32. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 (6)			0.3 0.45 1.0	V V V	I_{OL} = 100 μA (4) I_{OL} = 1.6 mA (4) I_{OL} = 3.5 mA (4)
V_{OL1}	Output Low Voltage, port 0 (6)			0.3 0.45 1.0	V V V	I_{OL} = 200 μA (4) I_{OL} = 3.2 mA (4) I_{OL} = 7.0 mA (4)
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 μA (4) I_{OL} = 1.6 mA (4) I_{OL} = 3.5 mA (4)
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -10 μA I_{OH} = -30 μA I_{OH} = -60 μA V_{CC} = 5 V ± 10%
V_{OH1}	Output High Voltage, port 0	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -200 μA I_{OH} = -3.2 mA I_{OH} = -7.0 mA V_{CC} = 5 V ± 10%
V_{OH2}	Output High Voltage,ALE, $\overline{PSEN}$	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -100 μA I_{OH} = -1.6 mA I_{OH} = -3.5 mA V_{CC} = 5 V ± 10%
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	μA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	μA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	μA	Vin = 2.0 V
C_{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I_{PD}	Power Down Current		20 (5)	50	μA	2.0 V < V_{CC} < 5.5 V (3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.4 Freq (MHz) @12MHz 5.8 @16MHz 7.4	mA	V_{CC} = 5.5 V (1)

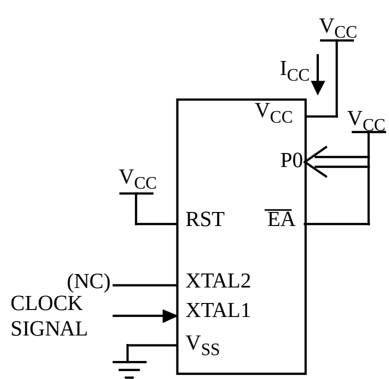
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	V_{CC} = 3.3 V(2)

NOTES

1. *I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 24.), $V_{IL} = V_{SS}$ + 0.5 V, $V_{IH} = V_{CC}$ - 0.5V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..*
2. *Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, $V_{IL} = V_{SS}$ + 0.5 V, $V_{IH} = V_{CC}$ - 0.5 V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 22.).*
3. *Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA} = V_{SS}$, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 23.).*
4. *Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.*
5. *Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.*
6. *Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:*
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:
   Port 0: 26 mA
   Ports 1, 2, 3 and 4 and 5 when available: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

7. *For other values, please contact your sales office.*
8. *Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 24.), $V_{IL} = V_{SS}$ + 0.5 V, $V_{IH} = V_{CC}$ - 0.5V; XTAL2 N.C.; $\overline{EA}$ = Port 0 = V_{CC}; RST = V_{SS}. The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.*



All other pins are disconnected.

Figure 20. I_{CC} Test Condition, under reset

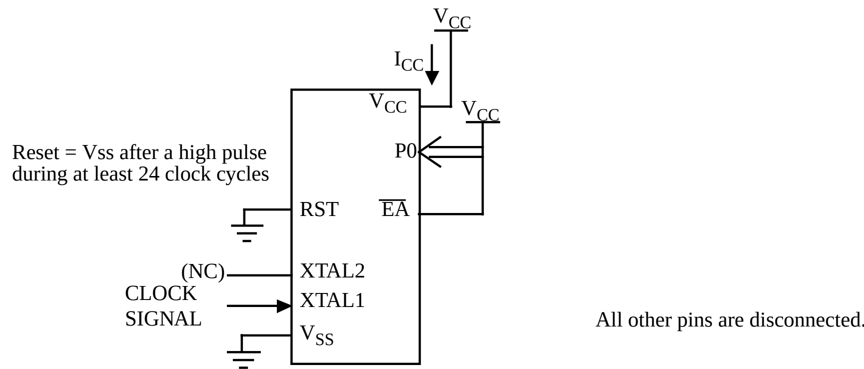


Figure 21. Operating I_{CC} Test Condition

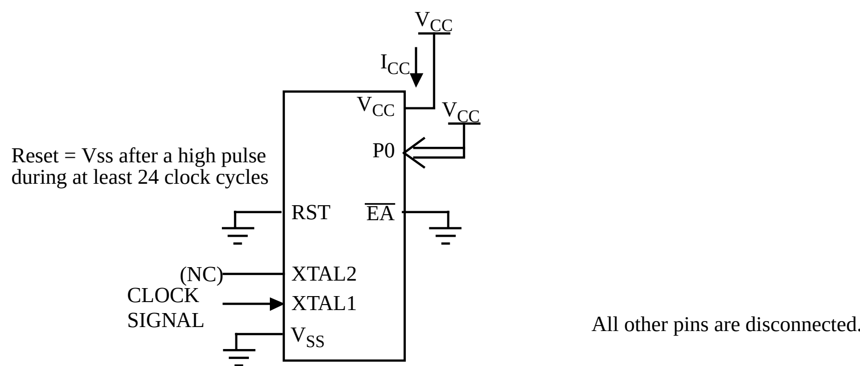


Figure 22. I_{CC} Test Condition, Idle Mode

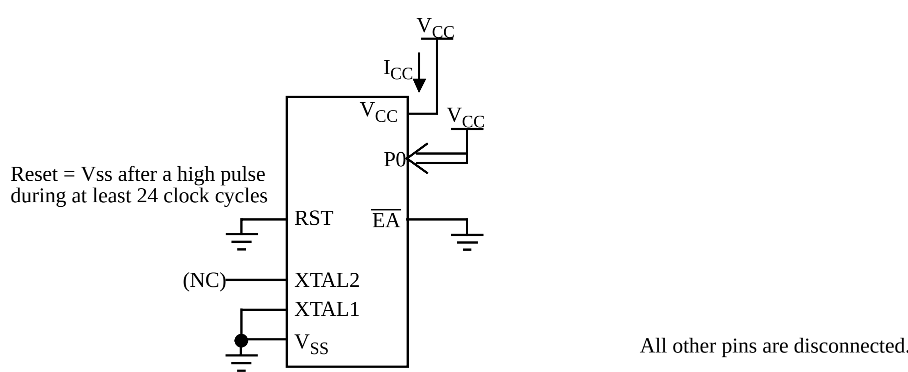


Figure 23. I_{CC} Test Condition, Power-Down Mode

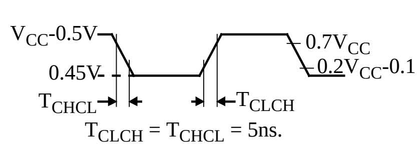


Figure 24. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes

10.5.2. External Program Memory Characteristics

Table 36. Symbol Description

Symbol	Parameter
T	Oscillator clock period
T_{LHLL}	ALE pulse width
T_{AVLL}	Address Valid to ALE
T_{LLAX}	Address Hold After ALE
T_{LLIV}	ALE to Valid Instruction In
T_{LLPL}	ALE to $\overline{PSEN}$
T_{PLPH}	$\overline{PSEN}$ Pulse Width
T_{PLIV}	$\overline{PSEN}$ to Valid Instruction In
T_{PXIX}	Input Instruction Hold After $\overline{PSEN}$
T_{PXIZ}	Input Instruction FloatAfter $\overline{PSEN}$
T_{PXAV}	$\overline{PSEN}$ to Address Valid
T_{AVIV}	Address to Valid Instruction In
T_{PLAZ}	$\overline{PSEN}$ Low to Address Float

Table 37. AC Parameters for Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T	25		33		25		50		33		ns
T_{LHLL}	40		25		42		35		52		ns
T_{AVLL}	10		4		12		5		13		ns
T_{LLAX}	10		4		12		5		13		ns
T_{LLIV}		70		45		78		65		98	ns
T_{LLPL}	15		9		17		10		18		ns
T_{PLPH}	55		35		60		50		75		ns
T_{PLIV}		35		25		50		30		55	ns
T_{PXIX}	0		0		0		0		0		ns
T_{PXIZ}		18		12		20		10		18	ns
T_{AVIV}		85		53		95		80		122	ns
T_{PLAZ}		10		10		10		10		10	ns

10.5.4. External Data Memory Characteristics

Table 39. Symbol Description

Symbol	Parameter
T_{RLRH}	$\overline{RD}$ Pulse Width
T_{WLWH}	$\overline{WR}$ Pulse Width
T_{RLDV}	$\overline{RD}$ to Valid Data In
T_{RHDX}	Data Hold After $\overline{RD}$
T_{RHDZ}	Data Float After $\overline{RD}$
T_{LLDV}	ALE to Valid Data In
T_{AVDV}	Address to Valid Data In
T_{LLWL}	ALE to $\overline{WR}$ or $\overline{RD}$
T_{AVWL}	Address to $\overline{WR}$ or $\overline{RD}$
T_{QVWX}	Data Valid to $\overline{WR}$ Transition
T_{QVWH}	Data set-up to $\overline{WR}$ High
T_{WHQX}	Data Hold After $\overline{WR}$
T_{RLAZ}	$\overline{RD}$ Low to Address Float
T_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE high

10.5.6. External Data Memory Read Cycle

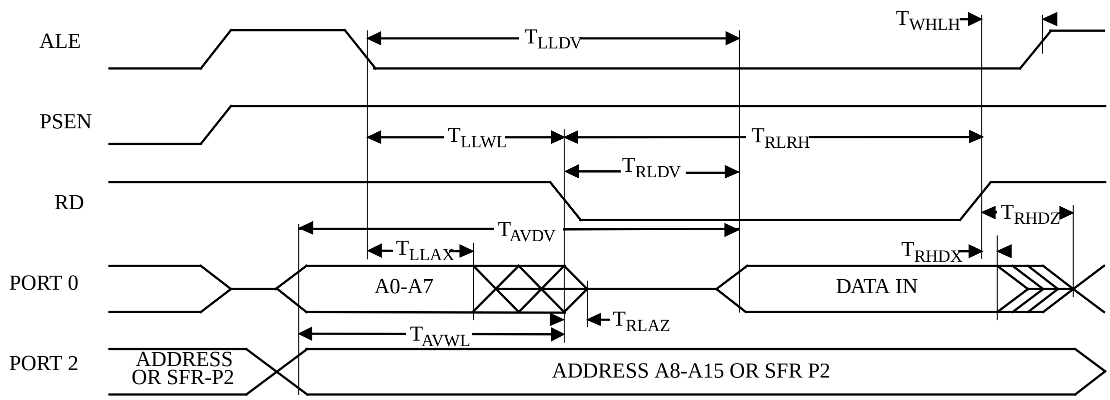


Figure 27. External Data Memory Read Cycle

10.5.7. Serial Port Timing - Shift Register Mode

Table 42. Symbol Description

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 43. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns